

REMARKS

Reconsideration of the application is requested in view of the above amendments and the following remarks. Applicants confirm the election of Subspecies I of Species I, upon which claims 1-4, 8-11 and 15-18 are readable. Based on the Examiner's most recent restriction, Applicants elect Group II, claims 2-4, 8-11 and 15-18, drawn to a slider scale package assembly flex circuit.

Claim 1 has been cancelled as being drawn to a non-elected slider scale package of new Group I. Applicants reserve the right to pursue the subject matter of claim 1 in a divisional application.

New claims 24-27 have been added as a method of supporting a slider/magnetic recording (MR) head in a disc drive. Applicants submit that claims 24-27 substantially correspond to the subject matter of claims 15-18. No new matter has been entered, and such claims are fully supported by the originally filed drawings, specification and claims.

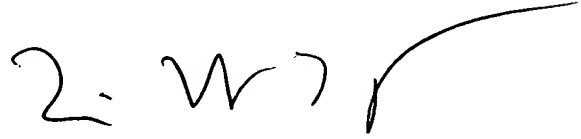
In view of the above, Applicants request reconsideration of the application in the form of a Notice of Allowance. If a phone conference would be helpful in resolving any issues related to this matter, please contact Applicant's Attorney below at 612.336.4755.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims

Claim 1 has been cancelled without prejudice or disclaimer.

Claim 17 has been amended and new claims 24-28 have been added as follows:

17. (Twice Amended) The HGA of claim 16, wherein the flex circuit includes first, second, third, and fourth interconnect pads wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pad, and the slider/MR head includes first, second, third, and fourth [interconnect bonds] bond pads wherein the at least one [interconnect] bond pad is one of the first, second, third or fourth [interconnect bonds] bond pads.

18. (Twice Amended) The HGA of claim 17, wherein the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads [of the flex circuit] match with polarities from the interconnect [bonds] pads.

Claims 24-27 are new.